

L22 ANSWER 1 OF 3 CAPLUS COPYRIGHT 2005 ACS on STN
AN 2003:550245 CAPLUS
DN 139:93834
ED Entered STN: 18 Jul 2003
TI Porous polyimide films, wiring board substrates therefrom, their manufacture, and electronic appliances therewith minimizing transmission loss
IN Ishikawa, Takao; Yamada, Shinji; Kawashima, Toshiyuki; Tahara, Shinji; Ikeda, Kenichi
PA Hitachi Ltd., Japan; Nitto Denko Corp.
SO Jpn. Kokai Tokkyo Koho, 9 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
IC ICM C08J009-28
ICS B32B015-08; H01L023-14; H05K001-03; H05K003-00; C08L079-08
CC 76-14 (Electric Phenomena)
Section cross-reference(s): 38

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 2003201363	A2	20030718	JP 2002-2000	20020109 <--
PRAI	JP 2002-2000		20020109		

CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
JP 2003201363	ICM	C08J009-28
	ICS	B32B015-08; H01L023-14; H05K001-03; H05K003-00; C08L079-08

AB The polyimide films consist of porous layers containing pores mainly of length $\geq 10 \mu\text{m}$ and satisfying dielec. constant ≤ 2.0 and dielec. tangent ≤ 0.003 , laminated on both sides with skin layers having more dense structure than the porous layers. The shape of pores is detailed. Wiring board substrates comprising conductor foils and the above films are also claimed. In the manufacturing process for the substrates, aromatic polyamic acid layers are formed on conductor foils, submerged in water, dried, and imidized.

ST porous polyimide copper laminate wiring board substrate; transmission loss porous polyimide copper laminate; gelated imidized polyamic acid porous film

IT Telephones

(cellular; porous polyimide films, printed circuit board substrates therefrom, their manufacture, and electronic appliances therewith)

IT Porous materials

(films; porous polyimide films, printed circuit board substrates therefrom, their manufacture, and electronic appliances therewith)

IT Printed circuit boards

(porous polyimide films, printed circuit board substrates therefrom, their manufacture, and electronic appliances therewith)

IT Films

(porous; porous polyimide films, printed circuit board substrates therefrom, their manufacture, and electronic appliances therewith)

IT Polyimides, uses

RL: DEV (Device component use); IMF (Industrial manufacture); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses) (porous; porous polyimide films, printed circuit board substrates therefrom, their manufacture, and electronic appliances therewith)

IT 74049-11-9P, 3,3',4,4'-Biphenyltetracarboxylic acid dianhydride-4,4'-diaminodiphenyl ether-p-phenylenediamine copolymer

RL: CPS (Chemical process); DEV (Device component use); IMF (Industrial manufacture); PEP (Physical, engineering or chemical process); TEM

(Technical or engineered material use); PREP (Preparation); PROC (Process); USES (Uses)
 (porous; porous polyimide films, printed circuit board substrates therefrom, their manufacture, and electronic appliances therewith)

IT 7440-50-8, Copper, processes
 RL: DEV (Device component use); PEP (Physical, engineering or chemical process); PYP (Physical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)
 (wiring layers; porous polyimide films, printed circuit board substrates therefrom, their manufacture, and electronic appliances therewith)

RN 74049-11-9P
 RN 7440-50-8

L22 ANSWER 2 OF 3 WPIX COPYRIGHT 2005 THE THOMSON CORP on STN
 AN 2004-084926 [09] WPIX
 DNN N2004-067733 DNC C2004-035137
 TI Porous polyimide film for printed wiring board used in mobile telephone, has specific dielectric constant and dielectric loss tangent, and is formed on both surfaces of porous layer.
 DC A26 A85 L03 P73 V04 W01 W02
 PA (HITA) HITACHI LTD; (NITL) NITTO DENKO CORP
 CYC 1
 PI JP 2003201363 A 20030718 (200409)* 9 C08J009-28 <--
 ADT JP 2003201363 A JP 2002-2000 20020109
 PRAI JP 2002-2000 20020109
 IC ICM C08J009-28
 ICS B32B015-08; H01L023-14; H05K001-03; H05K003-00
 ICI C08L079:08
 AB JP2003201363 A UPAB: 20040205
 NOVELTY - A porous polyimide film having dielectric constant of 2.0 or less and a dielectric loss tangent of 0.003 or less is formed on both the surfaces of the porous layer having hole (11) of length 10 m or more. The polyimide film is formed on copper foil on which a film of polyamic acid solution is applied.

DETAILED DESCRIPTION - INDEPENDENT CLAIMS are also included for the following:

- (1) porous polyimide wiring board;
- (2) porous polyimide substrate;
- (3) porous polyimide substrate manufacturing method;
- (4) porous polyimide film manufacturing method;
- (5) electronic component;
- (6) mobile telephone; and
- (7) high frequency transceiver.

USE - For electronic component (claimed), porous polyimide wiring board (claimed) used as high frequency circuit board, radio frequency (RF) circuit board in antenna such as rod antenna of portable communication apparatus e.g. mobile telephone (claimed). The high frequency circuit board is also used in high frequency transceiver (claimed), antenna of vehicle-mounted radar such as wireless radar, millimeter radar for motor vehicle, and satellite communication.

ADVANTAGE - The polyimide film has high porosity and high strength, by maintaining specific value of the dielectric constant value, hence the polyimide circuit board has low dielectric characteristics and low power consumption with improved reliability.

DESCRIPTION OF DRAWING(S) - The figure shows the sectional view of the porous polyimide wiring board.

Skin layer 6
 Sponge-like structure 7
 Holes 9-11
 Dwg. 4/8

FS CPI EPI GMPI
 FA AB; GI

MC CPI: A05-J01B; A10-D03; A11-B05C; A12-E07A; L03-H03; L03-H04E1
EPI: V04-R; W01-C01A1; W01-C01D3C; W02-A08B; W02-B07A

L22 ANSWER 3 OF 3 JAPIO (C) 2005 JPO on STN
AN 2003-201363 JAPIO
TI POROUS POLYIMIDE FILM, WIRING BOARD USING THE SAME, ITS MANUFACTURING
METHOD AND ITS USE
IN ISHIKAWA TAKAO; YAMADA SHINJI; KAWASHIMA TOSHIYUKI; TAWARA SHINJI; IKEDA
KENICHI
PA HITACHI LTD
NITTO DENKO CORP
PI JP 2003201363 A 20030718 Heisei
AI JP 2002-2000 (JP2002002000 Heisei) 20020109
PRAI JP 2002-2000 20020109
SO PATENT ABSTRACTS OF JAPAN (CD-ROM), Unexamined Applications, Vol. 2003
IC ICM C08J009-28
ICS B32B015-08; H01L023-14; H05K001-03; H05K003-00
ICI C08L079:08
AB PROBLEM TO BE SOLVED: To provide a porous polyimide film having a small
dielectric constant and a dielectric dissipation factor, to provide a
wiring board using the same, its manufacturing method and various uses
using the same.
SOLUTION: In the porous polyimide film that comprises a porous layer and a
skin layer which is formed on both surfaces of the porous layer and more
dense than in the porous layer, the porous layer has holes mostly of 10
 μ m length or more, the dielectric constant of 2.0 or less and the
dielectric dissipation factor of 0.003 or less. The wiring board using the
same, its manufacturing method, an electronic component, a mobile phone
and a high frequency transmitter-receiver using the same are provided.
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